

Network Solutions Oki for a Global Society

### FEDR27V6452G-02-06 Issue Date: Jul. 9, 2004

# OKI Semiconductor MR27V6452G

## 4M-Word $\times$ 16-Bit or 8M-Word $\times$ 8-Bit Page Mode P2ROM

### FEATURES

4,194,304-word × 16-bit / 8,388,608-word × 8-bit electrically switchable configuration
Page size of 8-word x 16-Bit or 16-word x 8-Bit
3.0 V to 3.6 V power supply
Random Access time 100 ns MAX
Page Access time 30 ns MAX
Operating current 50 mA MAX (5MHz)
Standby current 10 µA MAX
Input/Output TTL compatible
Three-state output

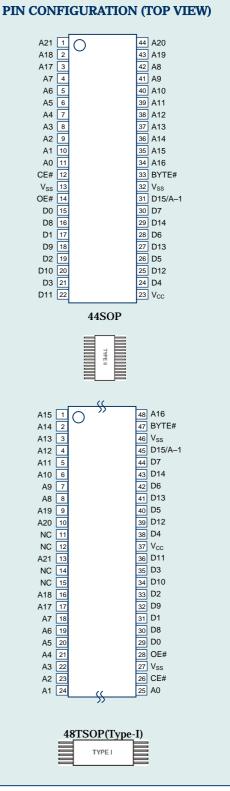
### PACKAGES

 MR27V6452G-xxxMA 44-pin plastic SOP (SOP44-P-600-1.27-K)
 MR27V6452G-xxxTN 48-pin plastic TSOP (TSOP I 48-P-1220-0.50-1K)

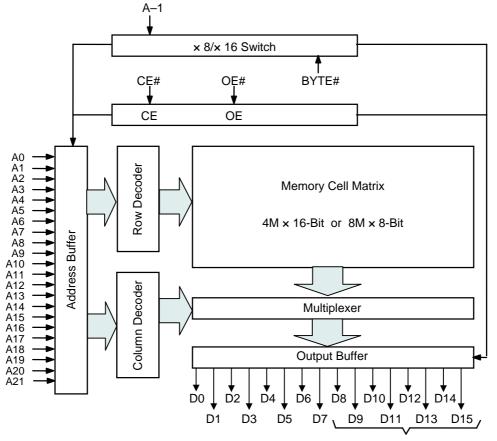
### P2ROM ADVANCED TECHNOLOGY

P2ROM stands for Production Programmed ROM. This exclusive Oki technology utilizes factory test equipment for programming the customers code into the P2ROM prior to final production testing. Advancements in this technology allows production costs to be equivalent to MASKROM and has many advantages and added benefits over the other non-volatile technologies, which include the following;

- Short lead time, since the P2ROM is programmed at the final stage of the production process, a large P2ROM inventory "bank system" of un-programmed packaged products are maintained to provide an aggressive lead-time and minimize liability as a custom product.
- **No mask charge**, since P2ROMs do not utilize a custom mask for storing customer code, no mask charges apply.
- No additional programming charge, unlike Flash and OTP that require additional programming and handling costs, the P2ROM already has the code loaded at the factory with minimal effect on the production throughput. The cost is included in the unit price.
- Custom Marking is available at no additional charge.
- **Pin Compatible with Mask ROM** and some FLASH products.



#### **BLOCK DIAGRAM**



In 8-bit output mode, these pins are placed in a high-Z state and pin D15 functions as the A-1 address pin.

#### **PIN DESCRIPTIONS**

Pin name	Functions
D15 / A–1	Data output / Address input
A0 to A21	Address inputs
D0 to D14	Data outputs
CE#	Chip enable input
OE#	Output enable input
BYTE#	Word / Byte select input
V <sub>CC</sub>	Power supply voltage
V <sub>SS</sub>	Ground
NC	No connect

### **FUNCTION TABLE**

Mode	CE#	OE#	BYTE#	V <sub>CC</sub>	D0 to D7	D8 to D14	D15/A–1
Read (16-Bit)	L	L	Н			D <sub>OUT</sub>	
Read (8-Bit)	L	L	L		D <sub>OUT</sub>	Hi–Z	L/H
			Н	3.3 V		Hi–Z	
Output disable	L	Н	L			*	
Otom dlavi			Н			11: 7	
Standby		H *	L			Hi–Z	*

\*: Don't Care (H or L)

### ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Condition	Value	Unit
Operating temperature under bias	Та		0 to 70	°C
Storage temperature	Tstg	_	-55 to 125	°C
Input voltage	VI		–0.5 to V <sub>CC</sub> +0.5	V
Output voltage	Vo	relative to $V_{SS}$	–0.5 to V <sub>CC</sub> +0.5	V
Power supply voltage	V <sub>CC</sub>		–0.5 to 5	V
Power dissipation per package	PD	Ta = 25°C	1.0	W
Output short circuit current	los	—	10	mA

### **RECOMMENDED OPERATING CONDITIONS**

(Ta = 0 to 70°C)

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
V <sub>CC</sub> power supply voltage	V <sub>CC</sub>		3.0		3.6	V
Input "H" level	V <sub>IH</sub>	$V_{CC}$ = 3.0 to 3.6 V	2.2		V <sub>CC</sub> +0.5*	V
Input "L" level	VIL		-0.5**		0.6	V

Voltage is relative to V<sub>SS</sub>.

\* : Vcc+1.5V(Max.) when pulse width of overshoot is less than 10ns.

\*\*: -1.5V(Min.) when pulse width of undershoot is less than 10ns.

### PIN CAPACITANCE

(V<sub>CC</sub> = 3.3 V, Ta = 25°C, f = 1 MHz)

				(100 0	e , ,	•,•••=)
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Input	C <sub>IN1</sub>	$V_1 = 0 V$	_	—	8	
BYTE#	C <sub>IN2</sub>	$v_1 = 0 v$	—	—	200	pF
Output	C <sub>OUT</sub>	$V_{O} = 0 V$	_	_	10	

#### **ELECTRICAL CHARACTERISTICS**

#### **DC** Characteristics

			(\	/ <sub>CC</sub> = 3.0 V	to 3.6 V, Ta	= 0 to 70°C)
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Input leakage current	ILI	$V_1 = 0$ to $V_{CC}$	—	_	10	μA
Output leakage current	I <sub>LO</sub>	$V_{O} = 0$ to $V_{CC}$	—	_	10	μA
V <sub>CC</sub> power supply current	Iccsc	$CE\# = V_{CC}$	—	_	10	μA
(Standby)	I <sub>CCST</sub>	$CE\# = V_{IH}$	—	_	1	mA
V <sub>CC</sub> power supply current (Read)	I <sub>CCA</sub>	$CE\# = V_{IL}, OE\# = V_{IH}$ f=5MHz	—	—	50	mA
Input "H" level	V <sub>IH</sub>	—	2.2	—	V <sub>CC</sub> +0.5*	V
Input "L" level	VIL	—	-0.5**	_	0.6	V
Output "H" level	V <sub>OH</sub>	I <sub>OH</sub> = -2 mA	2.4	_	_	V
Output "L" level	V <sub>OL</sub>	I <sub>OL</sub> = 4 mA	—	—	0.4	V

Voltage is relative to V<sub>SS</sub>.

\* : Vcc+1.5V(Max.) when pulse width of overshoot is less than 10ns.

\*\* : -1.5V(Min.) when pulse width of undershoot is less than 10ns.

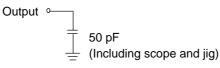
#### **AC Characteristics**

			(V <sub>CC</sub> =	3.0 V to 3.6 V, Ta	= 0 to 70°C)
Parameter	Symbol	Condition	Min.	Max.	Unit
Address cycle time	tc	—	100	—	ns
Address access time	t <sub>ACC</sub>	$CE\# = OE\# = V_{IL}$	_	100	ns
Page cycle time	t <sub>PC</sub>	—	30	—	ns
Page access time	t <sub>PAC</sub>	—	—	30	ns
CE# access time	t <sub>CE</sub>	$OE\# = V_{IL}$	—	100	ns
OE# access time	t <sub>OE</sub>	$CE\# = V_{IL}$	_	25	ns
Output disable time	t <sub>CHZ</sub>	$OE\# = V_{IL}$	0	20	ns
Output disable time	t <sub>OHZ</sub>	$CE\# = V_{IL}$	0	20	ns
Output hold time	t <sub>OH</sub>	$CE\# = OE\# = V_{IL}$	0		ns

Measurement conditions

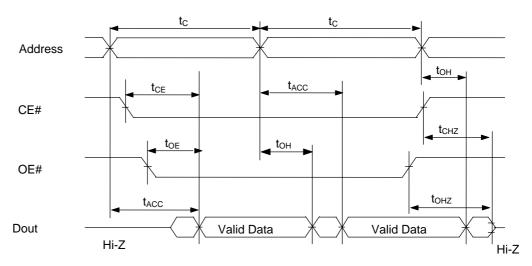
Input signal level	0 V/3.0 V
Input timing reference level	
Output load	
Output timing reference level	1/2Vcc

Output load

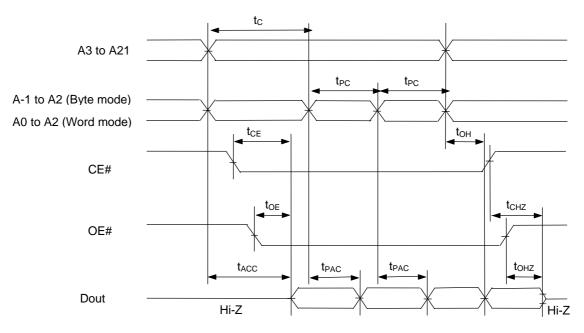


### TIMING CHART (READ CYCLE)

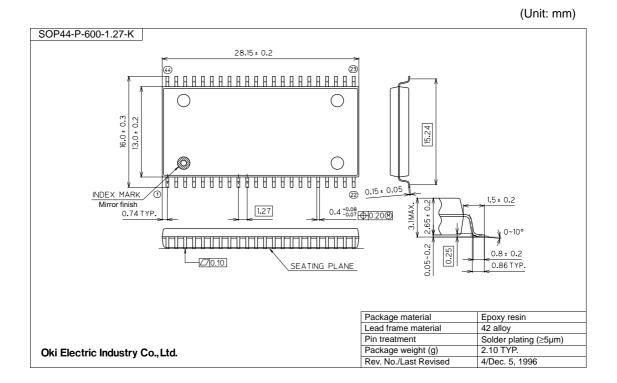
#### RANDOM ACCESS MODE READ CYCLE



#### PAGE ACCESS MODE READ CYCLE



#### PACKAGE DIMENSIONS



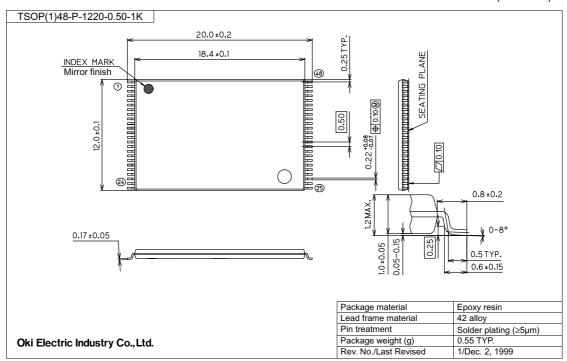
Notes for Mounting the Surface Mount Type Package

The surface mount type packages are very susceptible to heat in reflow mounting and humidity absorbed in storage.

Therefore, before you perform reflow mounting, contact Oki's responsible sales person for the product name, package name, pin number, package code and desired mounting conditions (reflow method, temperature and times).

#### **OKI** Semiconductor

MR27V6452G / P2ROM



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#### (Unit: mm)

### **REVISION HISTORY**

Document		Page			
No.	Date	Previous Edition	Current Edition	Description	
PEDR27V6452G-02-01	Jun., 2002	Ι	Ι	Preliminary edition 1	
FEDR27V6452G-02-01	Aug., 2002	-	-	Finally edition 1	
FEDR27V6452G-02-02	Nov., 2002	-	-	Added 48TSOPI package	
FEDR27V6452G-02-03	May., 2003	1	1	Change 48TSOP(1) package code to -1K	
FEDR27V6452G-02-04	Jun. 4, 2003	1,4	1,4	Change $t_{ACC}$ , $t_{PAC}$ to 100ns,30ns	
FEDR27V6452G-02-05	Jul. 16, 2003	4	4	Change t <sub>CHZ</sub> to 20ns	
FEDR27V6452G-02-06	Jul. 9, 2004	3	3	Add $P_D$ condition and $I_{OS} = 10mA$	

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